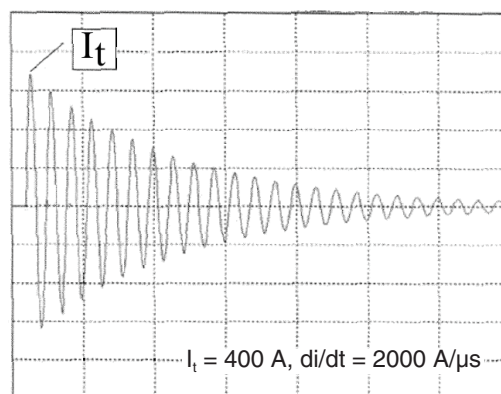
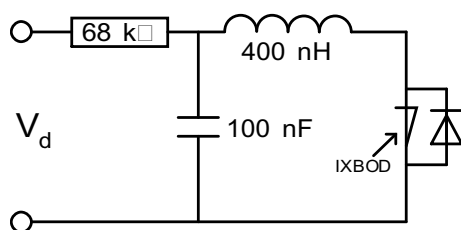
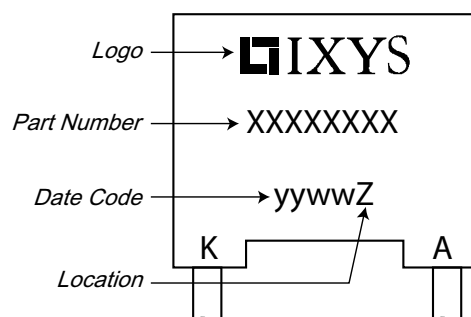


BOD2				Ratings			
Symbol	Definitions	Conditions	min.	typ.	max.		
I_D	drain current	$V_D = 0.8 \cdot V_{BO}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$			10 200	μA μA	
V_{BO}	breakover voltage	$V_{BO}(T_{VJ}) = V_{BO, 25^\circ\text{C}} [1 + K_T (T_{VJ} - 25^\circ\text{C})]$				V	
I_{RMS}	RMS current	$f = 50\text{ Hz}$ pins soldered to printed circuit (conductor 0.035x2mm) $T_{amb} = 50^\circ\text{C}$			1.4	A	
I_{FAVM}	maximum average forward current				0.9	A	
I_{SM}	maximum pulsed source current	$t_p = 0.1\text{ ms}$; non repetitive $T_{VJ} = 150^\circ\text{C}$			250	A	
I^2t	I^2t value for fusing	$t_p = 0.1\text{ ms}$ $T_{VJ} = 150^\circ\text{C}$			3.1	A^2s	
K_T	temperature coefficient of V_{BO}				$0.7 \cdot 10^{-3}$	K^{-1}	
K_P	coefficient for energy per pulse EP (material constant)				700	K/Ws	
R_{thJA}	thermal resistance junction to ambient	natural convection with air speed 2 m/s			60 45	K/W K/W	
I_{BO}	breakover current	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$			15 6	mA mA	
I_H	holding current	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$			20 12	mA mA	
V_H	holding voltage	$T_{VJ} = 25^\circ\text{C}$	4		8	V	
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = 0.9 \cdot V_{BO}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$			3000 1000	V/ μs V/ μs	
$(di/dt)_{cr}$	critical rate of rise of current	$I_T = 100\text{ A}$; $V_D = V_{BO}$; $f = 50\text{ Hz}$ $I_T = 600\text{ A}$; non repetitive $T_{VJ} = 150^\circ\text{C}$			200 500	A/ μs A/ μs	
t_q	turn-off time	$V_D = 0.75 \cdot V_{BO}$; $V_R = 0\text{ V}$; $I_T = 100\text{ A}$ $dv/dt_{(lin.)} = 5000\text{ V}/\mu\text{s}$; $di/dt = -500\text{ A}/\mu\text{s}$ $T_{VJ} = 125^\circ\text{C}$		200		μs	
V_T	forward voltage drop	$I_T = 10\text{ A}$ $T_{VJ} = 125^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$			1.3 1.2	V V	
V_{T0}	threshold voltage	for power-loss calculation only $T_{VJ} = 150^\circ\text{C}$			0.75	V	
r_T	slope resistance				0.05	Ω	



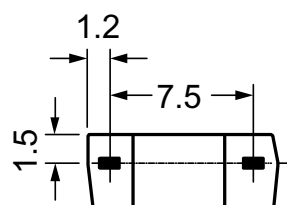
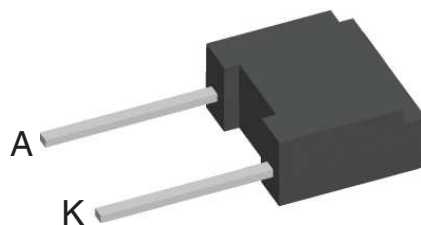
Package FP-Case			Ratings			
Symbol	Definitions	Conditions	min.	typ.	max.	
T_{amb}	ambient temperature (cooling medium)		-40		150	°C
T_{stg}	storage temperature		-40		150	°C
T_{VJM}	maximum virtual junction temperature		-40		150	°C
Weight				0.9		g

Product Marking



Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	IXBOD2-04	IXBOD2-04	Box	100	511174
Standard	IXBOD2-05	IXBOD2-05	Box	100	tbd
Standard	IXBOD2-06	IXBOD2-06	Box	100	tbd
Standard	IXBOD2-07	IXBOD2-07	Box	100	508425
Standard	IXBOD2-08	IXBOD2-08	Box	100	507602
Standard	IXBOD2-09	IXBOD2-09	Box	100	511668
Standard	IXBOD2-10	IXBOD2-10	Box	100	508078
Standard	IXBOD2-11	IXBOD2-11	Box	100	511860
Standard	IXBOD2-12	IXBOD2-12	Box	100	511675
Standard	IXBOD2-13	IXBOD2-13	Box	100	511682
Standard	IXBOD2-14	IXBOD2-14	Box	100	509782

Outlines FP-case



Dimensions in mm
(1 mm = 0.0394")

